

Notice of References Cited	Application/Control No. 10/593,809	Applicant(s)/Patent Under Reexamination NARAYAN ET AL.	
	Examiner JONATHAN C. LANGMAN	Art Unit 1794	Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-			
	B	US-			
	C	US-			
	D	US-			
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FOREIGN PATENT DOCUMENTS

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NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Catania et al., "Low resistivity body-centered cubic tantalum thin films as diffusion barriers between copper and silicon", J. Vac. Sci. Technol. A, Vol. 10, No. 5, 1992, pgs 3318-3321.
	V	Ino et al. "Ion energy, ion flux, and ion species effects on crystallographic and electrical properties of sputter deposited Ta thin films", J. Vac. Sci. Technol. A, Vol. 15, No. 5, 1997, pgs 2627-2635.
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